RENESAS

HSB83

Silicon Epitaxial Planar Diode for High Voltage Switching

REJ03G0187-0200Z (Previous: ADE-208-489A) Rev.2.00 Mar.22.2004

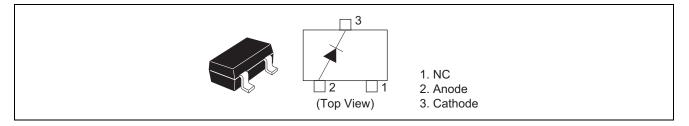
Features

- High reverse voltage. ($V_R = 250 \text{ V}$)
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Туре No.	Laser Mark	Package Code
HSB83	F7	CMPAK

Pin Arrangement





Absolute Maximum Ratings

			(Ta = 25°C)	
Item	Symbol	Value	Unit	
Peak reverse voltage	V _{RM}	300	V	
Reverse voltage	V _R	250	V	
Peak forward current	I _{FM}	300	mA	
Non-Repetitive peak forward surge current	I _{FSM} * ¹	2	А	
Average rectified current	lo	100	mA	
Junction temperature	Тј	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

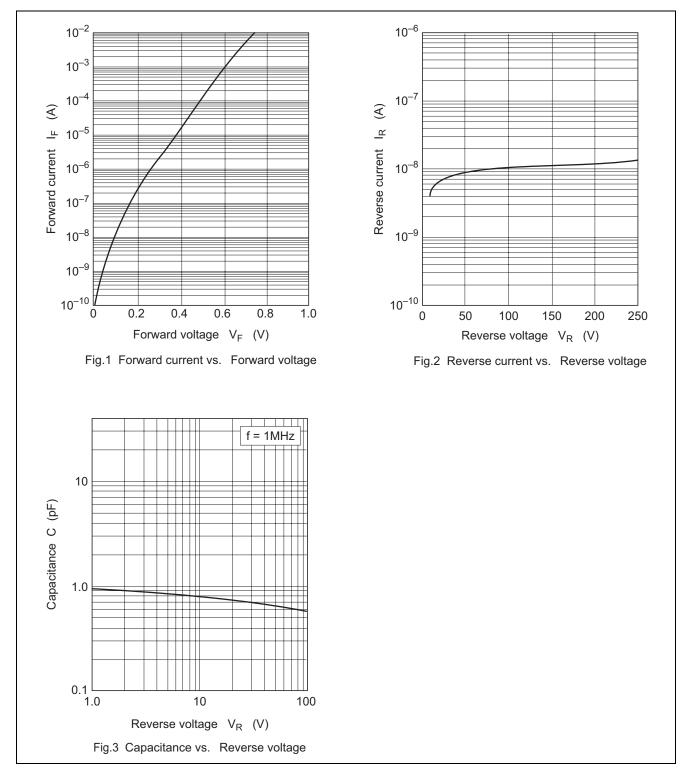
Note: 1. Value at duration of 10 ms.

Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	1.2	V	I _F = 100 mA
Reverse current	I _{R1}	_	—	0.2	μΑ	V _R = 250 V
	I _{R2}	_	—	100		V _R = 300 V
Capacitance	С	_	—	3.0	pF	$V_{R} = 0 V, f = 1 MHz$
Reverse recovery time	t _{rr}	—	_	100	ns	$I_F = I_R = 30 \text{ mA}, I_{rr} = 3 \text{ mA}, R_L = 100 \ \Omega$

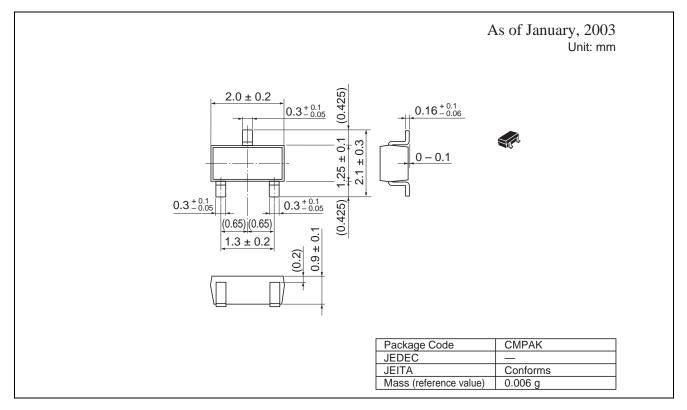


Main Characteristics



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Package Dimensions





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